

13TH WORLD CONGRESS ON ELECTRICAL ENGINEERING AND COMPUTER SYSTEMS AND SCIENCE (EECSS 2027)

August 15 – 17, 2027
Prague, Czech Republic

EECSS is aimed to become one of the leading international annual congresses in the fields of electrical engineering and computer systems and science. The congress is composed of 6 conferences. While each conference consists of an individual and separate theme, the 6 conferences share considerable overlap, which prompted the organization of this congress.

THE EECSS 2026 CONGRESS IS COMPOSED OF 6 CONFERENCES

- CIST²⁷** **CIST 2027** - 12th International Conference on Computer and Information Science and Technology
- MHCI²⁷** **MHCI 2027** - 14th International Conference on Multimedia and Human-Computer Interaction
- MVML²⁷** **MVML 2027** - 13th International Conference on Machine Vision and Machine Learning
- ICBES²⁷** **ICBES 2027** - 14th International Conference on Biomedical Engineering and Systems
- EEE²⁷** **EEE 2027** - 13th International Conference on Electrical Engineering and Electronics
- ICAIS²⁷** **ICAIS 2027** - 2nd International Conference on Artificial Intelligence and Intelligent Systems

Paper Submission Deadline
January 21, 2027

Early-Bird Registration
March 18, 2027



Dr. Luigi Benedicenti
University of New
Brunswick, Canada
Congress Chair



Dr. Zheng Liu
University of British Columbia,
Canada
Congress Co-Chair

Submission

- all submitted papers will be peer-reviewed
- the congress proceedings will be published under an ISSN and ISBN number
- each paper will be assigned a unique DOI number by [Crossref](#)
- the conference proceedings will be indexed by [Scopus](#), [Elsevier](#), [Google Scholar](#) and [Semantic Scholar](#)
- the proceedings will be permanently archived in [Portico](#) (one of the largest community-supported digital archives in the world).
- selected papers from the congress will be submitted for possible publication in one of the following journals [Journal of Machine Intelligence and Data Science \(JMIDS\)](#) or [Journal of Biomedical Engineering and Biosciences \(JBEB\)](#).







Scientific Committee Members

EEE 2027

Dr. Pantelis Capros, National Technical University of Athens, Greece
 Dr. Valentina Ciriani, University of Milan, Italy
 Dr. Riccardo Colella, National Research Council (CNR), Italy
 Dr. Edmond Cretu, University of British Columbia, Canada
 Dr. Zhirun Hu, The University of Manchester, UK
 Dr. Michał Jasiński Wrocław, University of Science and Technology, Poland

CIST 2027

Dr. José Carlos R. Alcantud, University of Salamanca, Spain
 Dr. Aparicio Carranza, New York City College of Technology, USA
 Dr. Luca Deri, University of Pisa, Italy
 Dr. Abdel Aziz Farrag (RET), Dalhousie University, Canada
 Dr. Sanmeet Kaur, Eastern Washington University, USA
 Dr. Michael N. Vrahatis, University of Patras, Greece
 Dr. Neli Zlatareva, Central Connecticut State University, USA

ICBES 2027

Dr. Gabriele Candiani, Politecnico di Milano, Italy
 Dr. Jordi Fonollosa, Universitat Politècnica de Catalunya, Spain
 Dr. Elba Mauriz García, University of León, Spain
 Dr. Peter Kneppo, Czech Technical University, Czech Republic
 Dr. Ivan T. Lima, North Dakota State University, USA
 Dr. Mehrab Mehrvar, Toronto Metropolitan University, Canada
 Dr. Michele Oliver, University of Guelph, Canada

MHCI 2027

Dr. Zoran Bojkovic, University of Belgrade, Serbia
 Dr. Nam Ju Kim, University of Miami, USA
 Dr. Dheerendra Mishra, Maulana Azad National Institute of Technology, India
 Dr. Hai Long Tran, DePaul University, USA
 Dr. Kazuhisa Yanaka, Kanagawa Institute of Technology, Japan

MVML 2027

Dr. Chamil Abeykoon, The University of Manchester, UK
 Dr. Jinzhu Gao, University of the Pacific, USA
 Dr. Natacha Gueorguieva, University of Massachusetts Dartmouth, USA
 Dr. Dalila B. Megherbi, University of Massachusetts Lowell, USA
 Dr. Kashif Naseer Qureshi, University of Limerick, Ireland
 Dr. KC Santosh, University of South Dakota, USA
 Dr. Jacek M. Zurada, The University of Louisville, USA

ICAIS 2027

- Dr. Shahram Payandeh, Simon Fraser University, USA
- Dr. Gerald Penn, University of Toronto, Canada
- Dr. Nicholas Costen, Manchester Metropolitan University, UK
- Dr. Jianbo Lu, Worcester Polytechnic Institute, USA